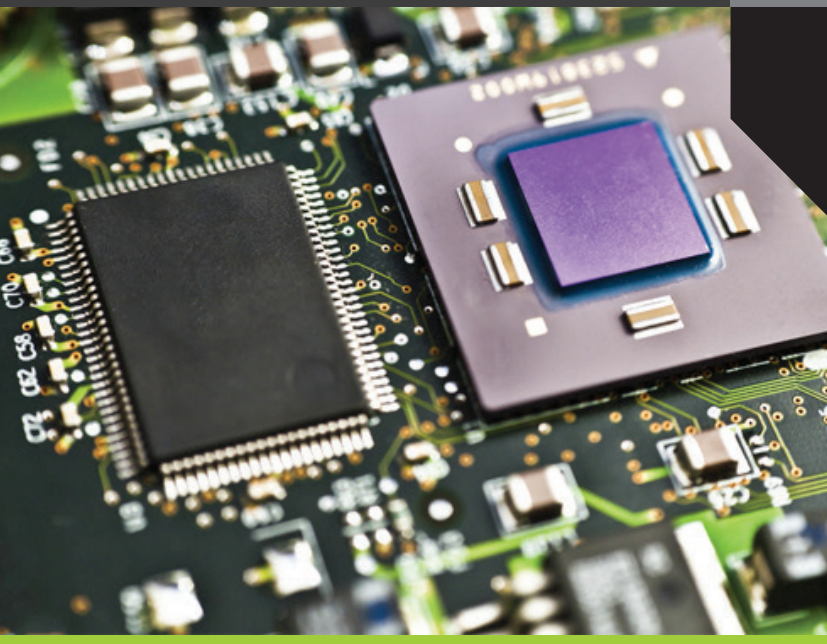


N₂ PURGING TECHNOLOGIES

MK2 IN LINE PURGING SYSTEM



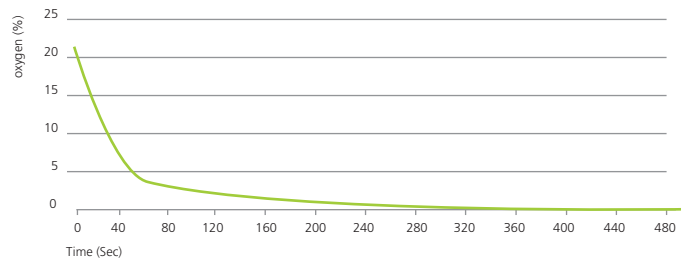
Semiconductor manufacturing processes often leave the processed wafer exposed to corrosion and/or adsorption of ambient gasses.

These gasses may corrode or change the electrical and mechanical properties of previous layers resulting in device failure.

Solutions Offered by RICOR Semiconductor Equipment Division:

- High purity purging systems that meet SEMI standards and are available as 'standalone' units or fully integrated into stockers with full communication of AMHS and OHV systems.
- The equipment has been designed and manufactured (including customization and field retrofit) in the following forms:
 - Standalone
 - Stocker integrated
 - Load port integrated

FOUP Oxygen level during purge down



SPECIFICATIONS

MK2

• Wafer size:	200/300
• Remote Control Recipe Based Purging Plan:	✓
• AMHS /PGV / AGV compatible:	✓
• Real Time Pressure andFlow monitoring and control:	✓
• Real Time O2 and relative Humidity monitoring and alarms:	✓
• Host equipment SECS II GEM communication compliance via HSMS:	✓
• Enhanced Carrier Handoff-Parallel I/O Interface:	✓
• Process Job Management (PJM):	
• Control Job Management (CJM):	
• RFID Sensing and Reporting:	✓
• Cleanliness – Class 1 @0.1 Micron:	✓
• Particle emission 0:	✓
• SEMI E84, E57, E64, E15, E87 compliance:	✓
• Purge Down Rate to 0.1% O2 < 6 min (25slpm, @25psi):	✓
• Safety – CE, Semi S2 Compliance:	✓
• L=455mm; H=1920, D=662mm, W=50KG:	

Specifications are subject to changes without prior notice.

CONTACTS

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